

# United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FI	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/659,379	09/11/2003		Motoaki Matsuda	Q77402	Q77402 2997	
23373	7590	08/16/2004		EXAMINER		
SUGHRUE	•	PLLC IA AVENUE, N.W.	NHU, DAVID			
SUITE 800	JILVAN	IA AVEITOE, IT.W.		ART UNIT	PAPER NUMBER	
WASHINGTON, DC 20037				2818		

DATE MAILED: 08/16/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)					
	10/659,379	MATSUDA, MOTOAKI					
Office Action Summary	Examiner	Art Unit					
	David Nhu	2818					
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	correspondence address					
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.1: after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply If NO period for reply is specified above, the maximum statutory period of Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be ting within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).					
Status							
1)⊠ Responsive to communication(s) filed on 19 Ju	ıly 2004.						
, =	action is non-final.						
3) Since this application is in condition for allowar							
Disposition of Claims							
4) ☐ Claim(s) 1-16 is/are pending in the application. 4a) Of the above claim(s) is/are withdray 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-16 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/o	wn from consideration.						
·· _	or .						
9) The specification is objected to by the Examiner.  10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.							
Applicant may not request that any objection to the							
Replacement drawing sheet(s) including the correct	*· ·						
11)☐ The oath or declaration is objected to by the Ex							
Priority under 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of:  1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority document	s have been received. s have been received in Applicati rity documents have been receive	ion No					
* See the attached detailed Office action for a list	of the certified copies not receive	ed.					
	Dan	12 Day					
Attachment(s)	_						
<ol> <li>Notice of References Cited (PTO-892)</li> <li>Notice of Draftsperson's Patent Drawing Review (PTO-948)</li> <li>Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date</li> </ol>	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal F 6) Other:						

Application/Control Number: 10/659,379

Art Unit: 2818

#### **DETAIL ACTIONS**

### Claims Objection

1. Claim 1, "by **means** of adhesive" should be --by an adhesive-- because the claim limitation is being invoking 35 USC 112, 6<sup>th</sup> paragraph by using the phrase "means". See MPEP 2181.

## Claim Rejections - 35 USC § 112

2. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

3. Claims 2-3, 7-15 are rejected under **35 U.S.C. 112, first paragraph**, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

It appears that the original specification does not have support for "wherein a first gap of said gaps is provided across a width of a first side of said two sides of said semiconductor chip that said first gap confronts (as cited in claim 2); wherein a first gap and a second gap of said gaps are provided across widths of the two sides of said semiconductor chip that said gaps confront (as cited in claim 3); a first gap between the stiffener and the substrate extending from a first position adjacent to a first side of the semiconductor chip to a first lateral side of the substrate (as cited in claim 7); further comprising a second gap between the stiffener and the substrate extending from a second position adjacent to a second side of the semiconductor chip to a second side of the substrate (as cited in claim 8); wherein the first and second sides of the semiconductor chip are opposite sides (as cited in claim 9); wherein the first gap comprises a

first depression formed in the first surface of the substrate (as cited in claim 10); wherein the first depression extends closer to the semiconductor chip than a portion of the stiffener arranged above the first depression (as cited in claim 11); wherein an adhesive connects the stiffener and the first surface of the substrate (as cited in claim 12); wherein the first gap comprises a first depression formed in a first surface of the stiffener facing the first surface of the substrate (as cited in claim 13); Wherein an adhesive connects the stiffener and the first surface of the substrate except that no adhesive is provided between the first depression in the first surface of the stiffener and the first surface of the substrate (as cited in claim 14); wherein a width of the first gap measured in a direction perpendicular to its direction of extension, is equal to a width of the first side of the semiconductor chip (as cited in claim 15)", which were not described/supported in the specifications.

Page 3

#### Conclusion

- 4. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure: Ovshinsky'711, Yamada'063 are cited as of interest.
- 5. A shortened statutory period for response to this action is set to expired 3 (three) months from the date of this letter. Failure to respond within the period for response will cause the application to become abandoned (see 710.02 (b)).
- 6. Any inquiry concerning this communication on earlier communications from the examiner should be directed to David Nhu, (571)272-1792. The examiner can normally be reached on Monday-Friday from 7:30 AM to 5:00 PM. The examiner's supervisor, David Nelms can be reached on (571)272-1787.

The fax phone number for the organization where this application or proceeding is assigned is (703)872-9306.

Art Unit: 2818

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956

David Nhu

PZ

August 3, 2004

Dair